

Series: Embedded NFC

#### **TECHNICAL DATA SHEET**

**Description**: 13.56MHz RFID/NFC SMD

Antenna

PART NUMBER: W3102



### Features:

- Antenna type coil on ferrite core
- Frequency 13.56MHz
- Inductance 4.7uH
- Read Distance 17mm
- Size 7.8 x 7 x 5 mm
- Fully SMD compatible
- RoHS Compliant
- MSL level 3

## **Applications:**

- RFID / NFC systems
- · Pairing, Sharing

All dimensions are in mm / inches

Issue: 1944

In the effort to improve our products, we reserve the right to make changes judged to be necessary. CONFIDENTIAL AND PROPRIETARY INFORMATION

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## **ELECTRICAL SPECIFICATIONS**

| Antenna Type      | coil                 |
|-------------------|----------------------|
| Frequency         | 13.56 MHz            |
| Nominal Impedance | $50~\Omega/80\Omega$ |
| Self inductance   | 4.7uH                |
| resistance        | $0.25\Omega$         |
| read distance     | 17mm                 |

### **MECHANICAL SPECIFICATIONS**

Size 7.8 X 7.0 X 5.0 mm

Weight 0.83 g

Antenna Material Core: 7.8 X 5.0(SH)DR B3.0

DR7.8 X 5.0 B3.0

Wire: 2UEW

## **ENVIRONMENTAL SPECIFICATIONS**

Operating Temperature  $-40 \sim +125^{\circ}$  C Storage Temperature  $-20 \sim +80^{\circ}$  C RoHS Compliant Yes





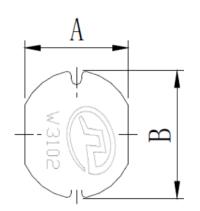
Description: 13.56MHz RFID/NFC SMD

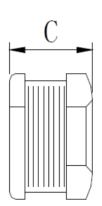
Antenna

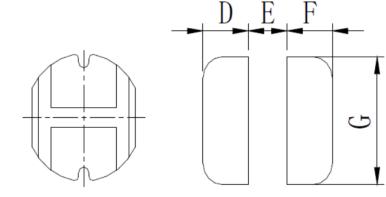
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## **MECHANICAL DRAWING**







Recommend Solder Dimension

|   | Dimension   | Α                 | В                 | С                  | D            | E            | F            | G            |
|---|-------------|-------------------|-------------------|--------------------|--------------|--------------|--------------|--------------|
| U | nit (mm/in) | 7.0±0.3/0.28±0.01 | 7.8±0.3/0.31±0.01 | 5.0±0.35/0.20±0.01 | 2.5/0.10 Ref | 2.7/0.11 Ref | 2.5/0.10 Ref | 7.5/0.30 Ref |



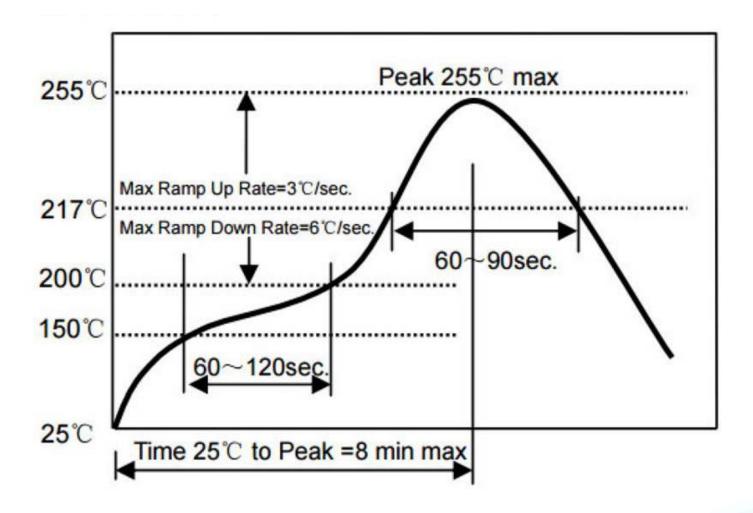
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# Reflow Soldering Temperature Profile Recommendation









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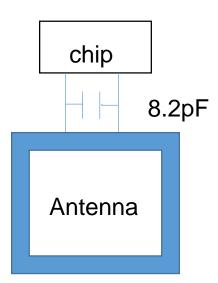
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# TEST SETUP



ACR card reader



Matching circuit



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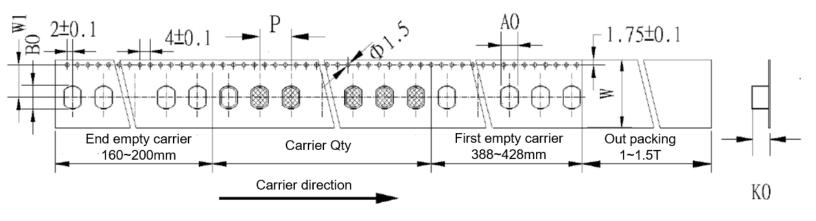
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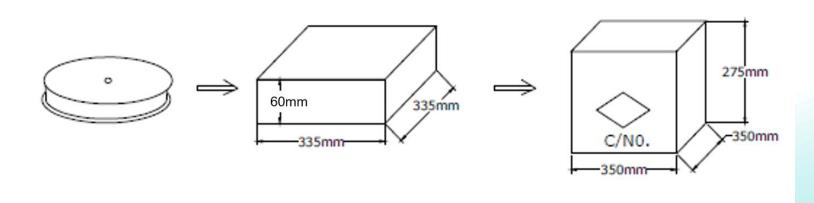
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### **PACKAGING**

1. Tape and reel packing with plastic vacuum bag.
1000 PCS/ REEL, 3 Reels/ Small BOX, 3 Small Boxes/ Big Box



| Type  | Carrier Size |      |     |    |      |      |      |
|-------|--------------|------|-----|----|------|------|------|
| Туре  | W            | W1   | T   | P  | A0   | В0   | КО   |
| W3102 | 16           | 12.5 | 0.4 | 12 | 7. 5 | 6. 1 | 9. 5 |



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2. MSL: Level 3

- 2.1 Calculated shelf life in sealed bag: 12 months at < 30°C and 60% relative humidity (RH)
  - 2.2 Peak temperature in reflow: 255 °C Max
- 2.3 After bag is opened, devices that will be subjected to reflow solder or other temperature process must:
  - a) Mount within: 168 hours of factory conditions ≤ 30 °C/60%
  - b) stored at < 20% RH
  - 2.4 Devices require bake, before mounting, if:
    - a) Humidity Indicator Card is > 20% when read at 23 ± 5 °C
    - b) 3a or 3b not met
  - 2.5 If baking is required, devices may be baked for 24 hours at 125~130 °C



# 单击下面可查看定价,库存,交付和生命周期等信息

# >>Pulse(普思)